

**Abstract**

A method of forming a low dielectric constant structure. The method comprises providing at 5 a first temperature a dielectric material having a first dielectric constant and a first elastic modulus, and curing the dielectric material by a thermal curing process, in which the material is heated to a second temperature by increasing the temperature at an average rate of at least 1 °C per second. As a result a densified, dielectric material is obtained which has a low dielectric constant.